

- Electrical features
 - $V_{CES} = 1200\text{ V}$
 - $I_{C\text{ nom}} = 800\text{ A} / I_{CRM} = 1600\text{ A}$
 - TRENCHSTOP™ IGBT7
 - $V_{CE,sat}$ with positive temperature coefficient
- Mechanical features
 - Standard housing
 - 4 kV AC 1 min insulation
 - High creepage and clearance distances
 - High power density
 - Isolated base plate
 - Package with CTI > 400



- Three-level applications
- Commercial agriculture vehicles
- High-power converters
- Motor drives
- Servo drives
- Solar applications
- UPS systems

- Qualified for industrial applications according to the relevant tests of IEC 60747, 60749 and 60068

The diagram shows a full-bridge rectifier circuit. It consists of four semiconductor devices arranged in a bridge configuration: two thyristors (top and bottom) and two diodes (left and right). The thyristors have their gates connected to their anodes. The diodes are connected in anti-parallel to the thyristors. The input terminals are at the top, and the output terminals are at the bottom. The thyristors are connected to the positive output terminal, and the diodes are connected to the negative output terminal.

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1 Package

Table 1 Insulation coordination

Parameter	Symbol	Note or test condition	Values	Unit
Isolation test voltage	V_{ISOL}	RMS, $f = 50 \text{ Hz}$, $t = 60 \text{ s}$	4.0	kV
Material of module baseplate			Cu	
Internal isolation		basic insulation (class 1, IEC 61140)	Al_2O_3	
Creepage distance	d_{Creep}	terminal to heatsink	29.0	mm
Creepage distance	d_{Creep}	terminal to terminal	23.0	mm
Clearance	d_{Clear}	terminal to heatsink	23.0	mm
Clearance	d_{Clear}	terminal to terminal	11.0	mm
Comparative tracking index	CTI		> 400	
Relative thermal index (electrical)	RTI	housing	140	°C

Table 2 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Stray inductance module	L_{sCE}			20		nH
Module lead resistance, terminals - chip	$R_{CC'+EE'}$	$T_C = 25^\circ\text{C}$, per switch		0.5		mΩ
Storage temperature	T_{stg}		-40		125	°C
Mounting torque for module mounting	M	- Mounting according to valid application note	M5, Screw	3	6	Nm
Terminal connection torque	M	- Mounting according to valid application note	M6, Screw	2.5	5	Nm
Weight	G			340		g

2 IGBT, Inverter

Table 3 Maximum rated values

Parameter	Symbol	Note or test condition		Values	Unit
Collector-emitter voltage	V_{CES}		$T_{vj} = 25^\circ\text{C}$	1200	V
Continuous DC collector current	I_{CDC}	$T_{vj \max} = 175^\circ\text{C}$	$T_C = 90^\circ\text{C}$	800	A
Maximum RMS module DC-terminal current	I_{tRMS}		$T_{\text{Terminal}} = 115^\circ\text{C}$, $T_C = 90^\circ\text{C}$	650	A
			$T_{\text{Terminal}} = 115^\circ\text{C}$, $T_C = 115^\circ\text{C}$	600	

(table continues...)
 Datasheet

Table 3 (continued) Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit
Repetitive peak collector current	I_{CRM}	t_p limited by $T_{vj\ op}$	1600	A
Gate-emitter peak voltage	V_{GES}		± 20	V

Table 4 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Collector-emitter saturation voltage	$V_{CE\ sat}$	$I_C = 800\ A, V_{GE} = 15\ V$	$T_{vj} = 25\ ^\circ C$	1.50	1.75	V
			$T_{vj} = 125\ ^\circ C$	1.65		
			$T_{vj} = 150\ ^\circ C$	1.70		
			$T_{vj} = 175\ ^\circ C$	1.75		
Gate threshold voltage	V_{GETh}	$I_C = 16\ mA, V_{CE} = V_{GE}, T_{vj} = 25\ ^\circ C$	5.15	5.80	6.45	V
Gate charge	Q_G	$V_{GE} = \pm 15\ V, V_{CC} = 600\ V$		12.8		μC
Internal gate resistor	R_{Gint}	$T_{vj} = 25\ ^\circ C$		0.43		Ω
Input capacitance	C_{ies}	$f = 100\ kHz, T_{vj} = 25\ ^\circ C, V_{CE} = 25\ V, V_{GE} = 0\ V$		122		nF
Reverse transfer capacitance	C_{res}	$f = 100\ kHz, T_{vj} = 25\ ^\circ C, V_{CE} = 25\ V, V_{GE} = 0\ V$		0.6		nF
Collector-emitter cut-off current	I_{CES}	$V_{CE} = 1200\ V, V_{GE} = 0\ V, T_{vj} = 25\ ^\circ C$			0.1	mA
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0\ V, V_{GE} = 20\ V, T_{vj} = 25\ ^\circ C$			100	nA
Turn-on delay time (inductive load)	t_{don}	$I_C = 800\ A, V_{CC} = 600\ V, V_{GE} = \pm 15\ V, R_{Gon} = 0.51\ \Omega$	$T_{vj} = 25\ ^\circ C$	0.500		μs
			$T_{vj} = 125\ ^\circ C$	0.517		
			$T_{vj} = 150\ ^\circ C$	0.522		
			$T_{vj} = 175\ ^\circ C$	0.527		
Rise time (inductive load)	t_r	$I_C = 800\ A, V_{CC} = 600\ V, V_{GE} = \pm 15\ V, R_{Gon} = 0.51\ \Omega$	$T_{vj} = 25\ ^\circ C$	0.065		μs
			$T_{vj} = 125\ ^\circ C$	0.073		
			$T_{vj} = 150\ ^\circ C$	0.075		
			$T_{vj} = 175\ ^\circ C$	0.077		
Turn-off delay time (inductive load)	t_{doff}	$I_C = 800\ A, V_{CC} = 600\ V, V_{GE} = \pm 15\ V, R_{Goff} = 0.51\ \Omega$	$T_{vj} = 25\ ^\circ C$	0.544		μs
			$T_{vj} = 125\ ^\circ C$	0.628		
			$T_{vj} = 150\ ^\circ C$	0.652		
			$T_{vj} = 175\ ^\circ C$	0.675		

(table continues...)

Table 4 (continued) Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Fall time (inductive load)	t_f	$I_C = 800 \text{ A}$, $V_{CC} = 600 \text{ V}$, $V_{GE} = \pm 15 \text{ V}$, $R_{Goff} = 0.51 \Omega$	$T_{vj} = 25 \text{ }^\circ\text{C}$	0.122		μs
			$T_{vj} = 125 \text{ }^\circ\text{C}$	0.260		
			$T_{vj} = 150 \text{ }^\circ\text{C}$	0.310		
			$T_{vj} = 175 \text{ }^\circ\text{C}$	0.360		
Turn-on energy loss per pulse	E_{on}	$I_C = 800 \text{ A}$, $V_{CC} = 600 \text{ V}$, $L_\sigma = 25 \text{ nH}$, $V_{GE} = \pm 15 \text{ V}$, $R_{Gon} = 0.51 \Omega$, $di/dt = 8700 \text{ A}/\mu\text{s}$ ($T_{vj} = 175 \text{ }^\circ\text{C}$)	$T_{vj} = 25 \text{ }^\circ\text{C}$	27.2		mJ
			$T_{vj} = 125 \text{ }^\circ\text{C}$	42.7		
			$T_{vj} = 150 \text{ }^\circ\text{C}$	48.7		
			$T_{vj} = 175 \text{ }^\circ\text{C}$	54.6		
Turn-off energy loss per pulse	E_{off}	$I_C = 800 \text{ A}$, $V_{CC} = 600 \text{ V}$, $L_\sigma = 25 \text{ nH}$, $V_{GE} = \pm 15 \text{ V}$, $R_{Goff} = 0.51 \Omega$, $dv/dt = 3400 \text{ V}/\mu\text{s}$ ($T_{vj} = 175 \text{ }^\circ\text{C}$)	$T_{vj} = 25 \text{ }^\circ\text{C}$	69.7		mJ
			$T_{vj} = 125 \text{ }^\circ\text{C}$	108		
			$T_{vj} = 150 \text{ }^\circ\text{C}$	120		
			$T_{vj} = 175 \text{ }^\circ\text{C}$	132		
SC data	I_{SC}	$V_{GE} \leq 15 \text{ V}$, $V_{CC} = 800 \text{ V}$, $V_{CEmax} = V_{CES} - L_{sCE} \cdot di/dt$	$t_p \leq 8 \mu\text{s}$, $T_{vj} = 150 \text{ }^\circ\text{C}$	3000		A
			$t_p \leq 6 \mu\text{s}$, $T_{vj} = 175 \text{ }^\circ\text{C}$	2700		
Thermal resistance, junction to case	R_{thJC}	per IGBT			0.0483	K/W
Thermal resistance, case to heat sink	R_{thCH}	per IGBT		0.0251		K/W
Temperature under switching conditions	$T_{vj op}$		-40		175	$^\circ\text{C}$

Note: $T_{vj op} > 150 \text{ }^\circ\text{C}$ is allowed for operation at overload conditions. For detailed specifications, please refer to AN 2018-14.

3 Diode, Inverter

Table 5 Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit
Repetitive peak reverse voltage	V_{RRM}	$T_{vj} = 25 \text{ }^\circ\text{C}$	1200	V
Continuous DC forward current	I_F		800	A
Repetitive peak forward current	I_{FRM}	$t_p = 1 \text{ ms}$	1600	A

(table continues...)

Table 5 (continued) Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit
I^2t - value	I^2t	$t_p = 10 \text{ ms}$, $V_R = 0 \text{ V}$	$T_{vj} = 125^\circ\text{C}$	A^2s
			$T_{vj} = 175^\circ\text{C}$	
			53000	
			41000	

Table 6 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Forward voltage	V_F	$I_F = 800 \text{ A}$, $V_{GE} = 0 \text{ V}$	$T_{vj} = 25^\circ\text{C}$	1.80	2.10	V
			$T_{vj} = 125^\circ\text{C}$	1.70		
			$T_{vj} = 150^\circ\text{C}$	1.65		
			$T_{vj} = 175^\circ\text{C}$	1.60		
Peak reverse recovery current	I_{RM}	$V_{CC} = 600 \text{ V}$, $I_F = 800 \text{ A}$, $V_{GE} = -15 \text{ V}$, $-di_F/dt = 8700 \text{ A}/\mu\text{s}$ ($T_{vj} = 175^\circ\text{C}$)	$T_{vj} = 25^\circ\text{C}$	540		A
			$T_{vj} = 125^\circ\text{C}$	720		
			$T_{vj} = 150^\circ\text{C}$	765		
			$T_{vj} = 175^\circ\text{C}$	810		
Recovered charge	Q_r	$V_{CC} = 600 \text{ V}$, $I_F = 800 \text{ A}$, $V_{GE} = -15 \text{ V}$, $-di_F/dt = 8700 \text{ A}/\mu\text{s}$ ($T_{vj} = 175^\circ\text{C}$)	$T_{vj} = 25^\circ\text{C}$	62		μC
			$T_{vj} = 125^\circ\text{C}$	117		
			$T_{vj} = 150^\circ\text{C}$	137		
			$T_{vj} = 175^\circ\text{C}$	156		
Reverse recovery energy	E_{rec}	$V_{CC} = 600 \text{ V}$, $I_F = 800 \text{ A}$, $V_{GE} = -15 \text{ V}$, $-di_F/dt = 8700 \text{ A}/\mu\text{s}$ ($T_{vj} = 175^\circ\text{C}$)	$T_{vj} = 25^\circ\text{C}$	27.9		mJ
			$T_{vj} = 125^\circ\text{C}$	54.5		
			$T_{vj} = 150^\circ\text{C}$	63.3		
			$T_{vj} = 175^\circ\text{C}$	72.1		
Thermal resistance, junction to case	R_{thJC}	per diode			0.0892	K/W
Thermal resistance, case to heat sink	R_{thCH}	per diode		0.0333		K/W
Temperature under switching conditions	$T_{vj\text{op}}$		-40		175	$^\circ\text{C}$

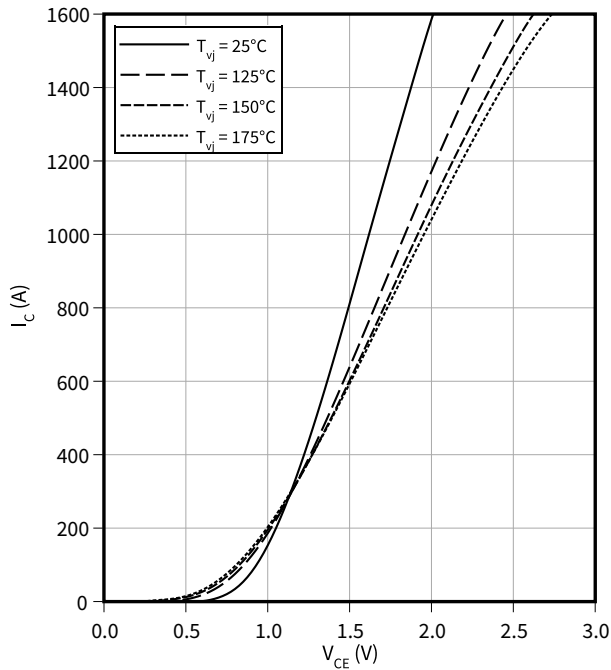
Note: $T_{vj\text{op}} > 150^\circ\text{C}$ is allowed for operation at overload conditions. For detailed specifications, please refer to AN 2018-14.

4 Characteristics diagrams

Output characteristic (typical), IGBT, Inverter

$I_C = f(V_{CE})$

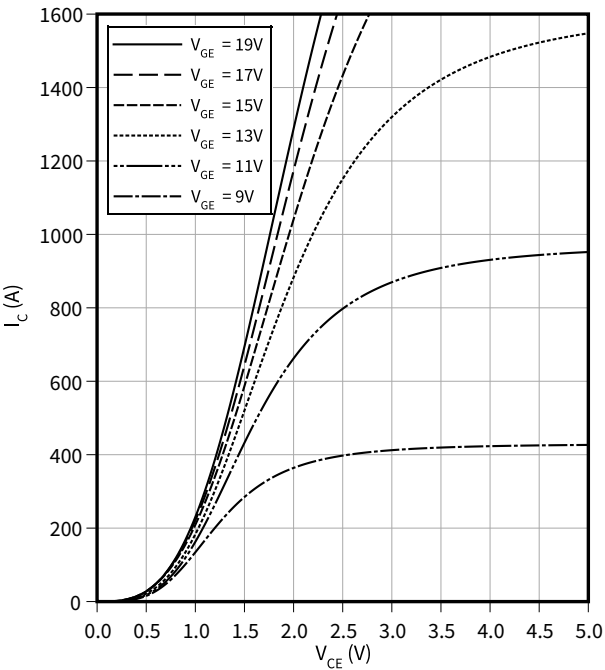
$V_{GE} = 15\text{ V}$



Output characteristic field (typical), IGBT, Inverter

$I_C = f(V_{CE})$

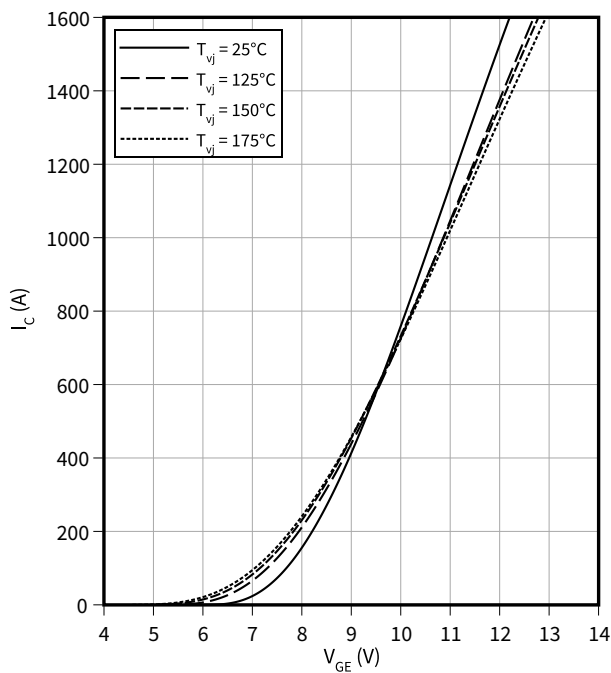
$T_{vj} = 175^\circ\text{C}$



Transfer characteristic (typical), IGBT, Inverter

$I_C = f(V_{GE})$

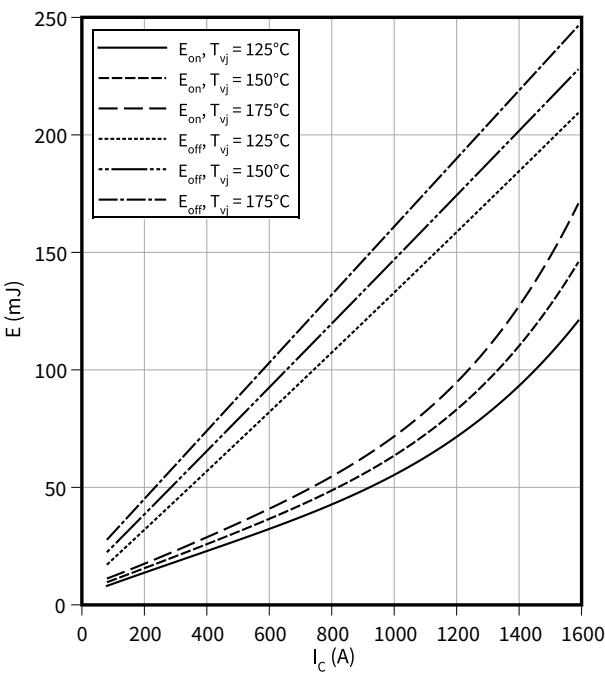
$V_{CE} = 20\text{ V}$



Switching losses (typical), IGBT, Inverter

$E = f(I_C)$

$R_{Goff} = 0.51\ \Omega$, $R_{Gon} = 0.51\ \Omega$, $V_{CC} = 600\text{ V}$, $V_{GE} = \pm 15\text{ V}$

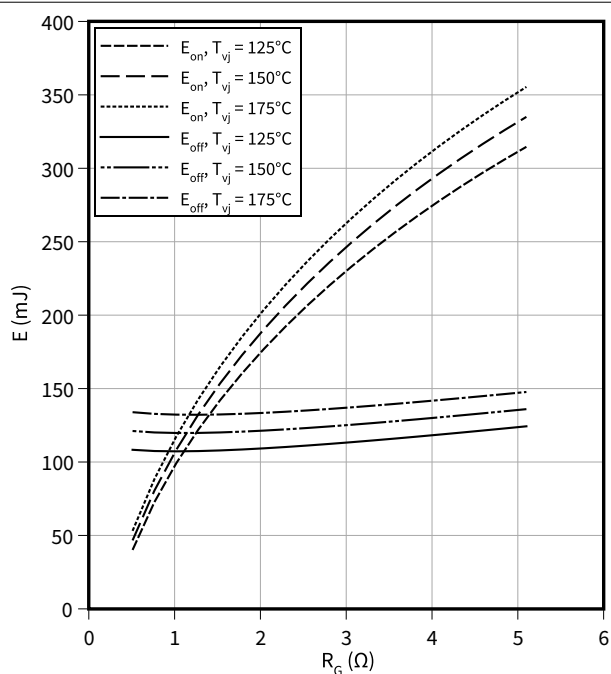


4 Characteristics diagrams

Switching losses (typical), IGBT, Inverter

$$E = f(R_G)$$

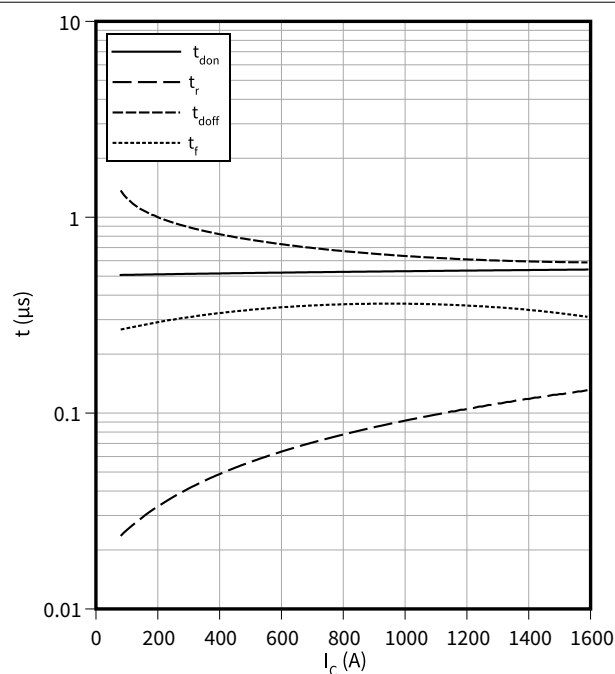
$I_C = 800 \text{ A}$, $V_{CC} = 600 \text{ V}$, $V_{GE} = \pm 15 \text{ V}$



Switching times (typical), IGBT, Inverter

$$t = f(I_C)$$

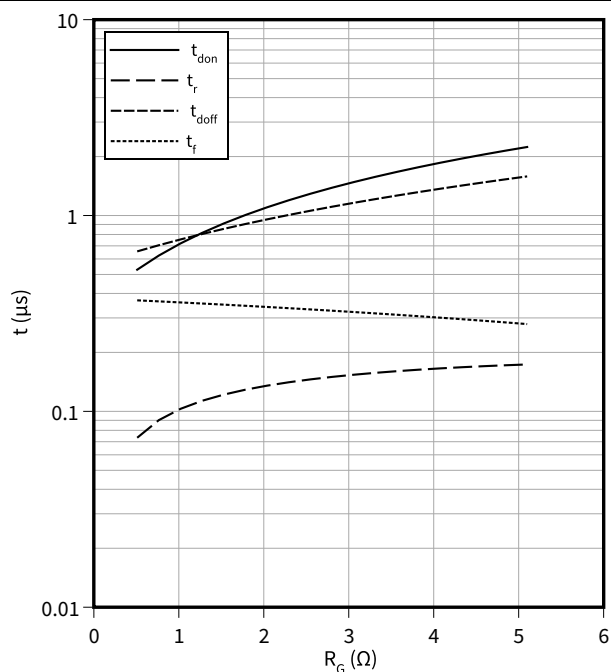
$R_{Goff} = 0.51 \Omega$, $R_{Gon} = 0.51 \Omega$, $V_{CC} = 600 \text{ V}$, $V_{GE} = \pm 15 \text{ V}$, $T_{vj} = 175^\circ\text{C}$



Switching times (typical), IGBT, Inverter

$$t = f(R_G)$$

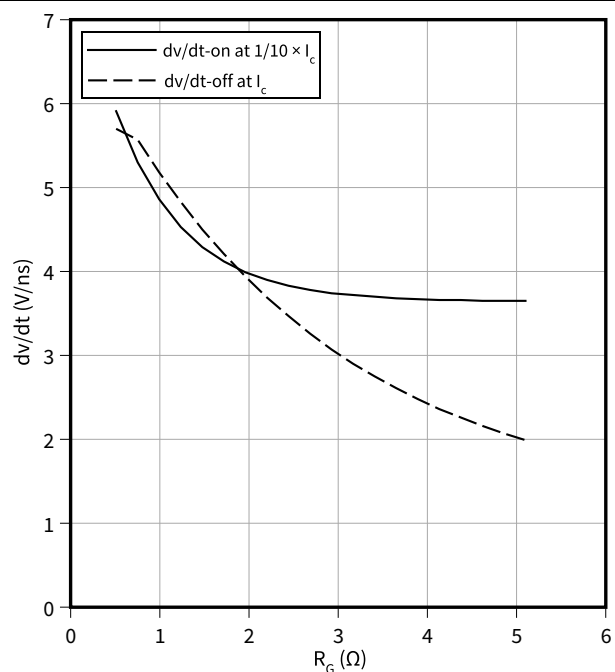
$I_C = 800 \text{ A}$, $V_{CC} = 600 \text{ V}$, $V_{GE} = \pm 15 \text{ V}$, $T_{vj} = 175^\circ\text{C}$



Voltage slope (typical), IGBT, Inverter

$$dv/dt = f(R_G)$$

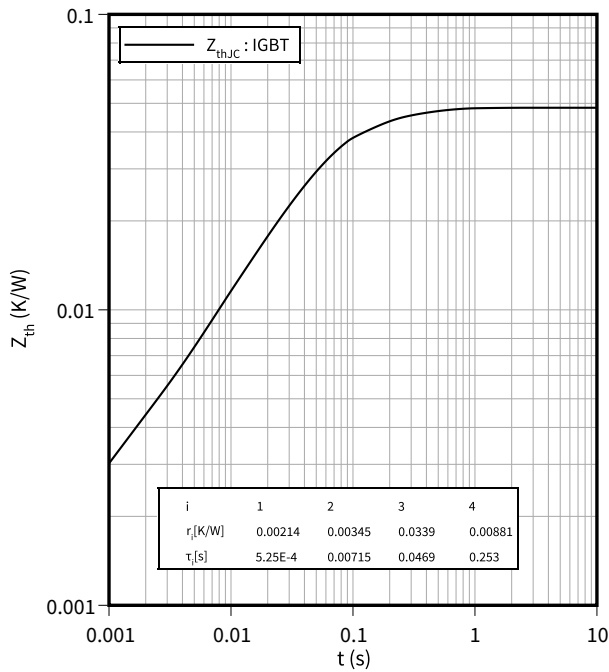
$I_C = 800 \text{ A}$, $V_{CC} = 600 \text{ V}$, $V_{GE} = \pm 15 \text{ V}$, $T_{vj} = 25^\circ\text{C}$



4 Characteristics diagrams

Transient thermal impedance , IGBT, Inverter

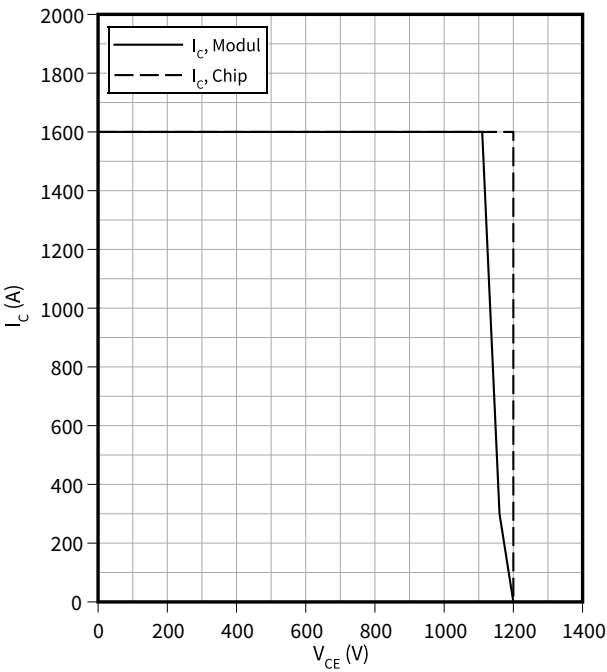
$Z_{th} = f(t)$



Reverse bias safe operating area (RBSOA), IGBT, Inverter

$I_C = f(V_{CE})$

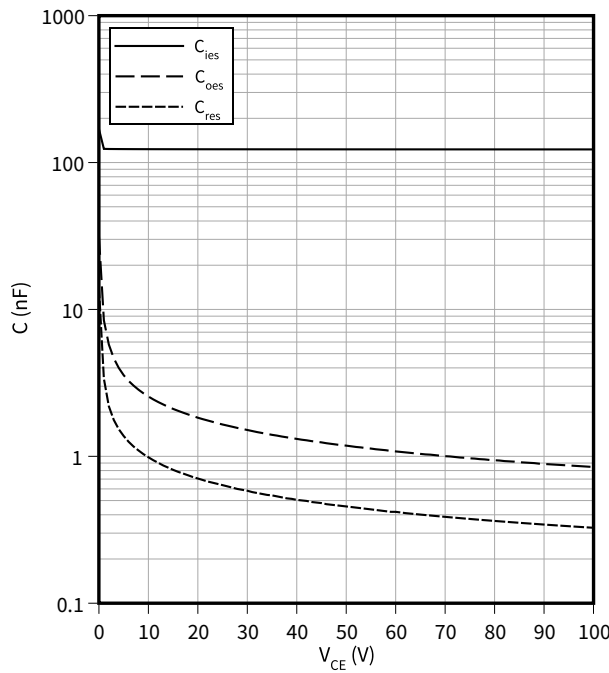
$R_{Goff} = 0.51 \Omega, V_{GE} = \pm 15 V, T_{vj} = 175 ^\circ C$



Capacity characteristic (typical), IGBT, Inverter

$C = f(V_{CE})$

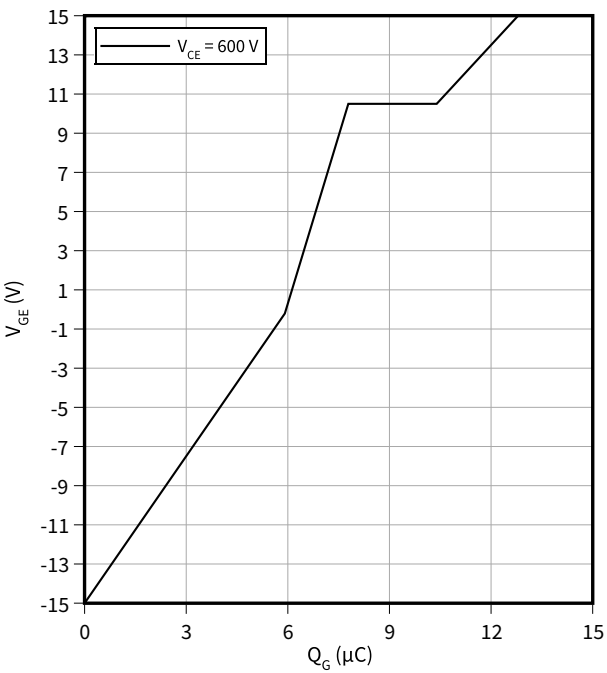
$f = 100 \text{ kHz}, V_{GE} = 0 V, T_{vj} = 25 ^\circ C$



Gate charge characteristic (typical), IGBT, Inverter

$V_{GE} = f(Q_G)$

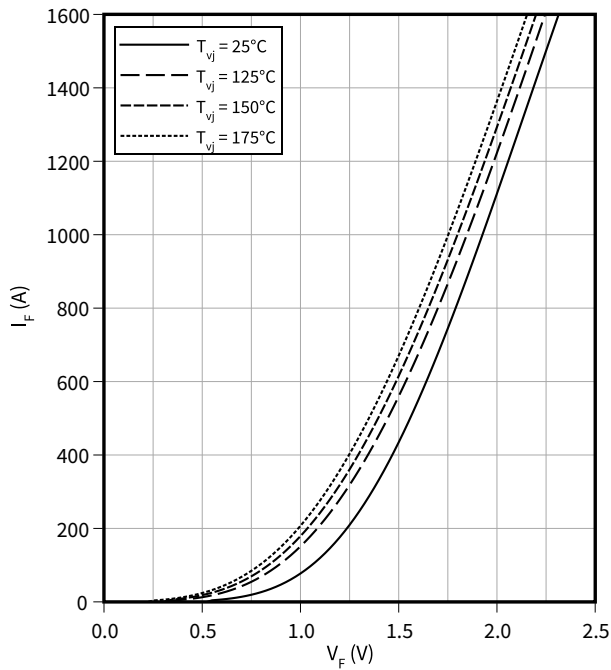
$I_C = 800 A, T_{vj} = 25 ^\circ C$



4 Characteristics diagrams

Forward characteristic (typical), Diode, Inverter

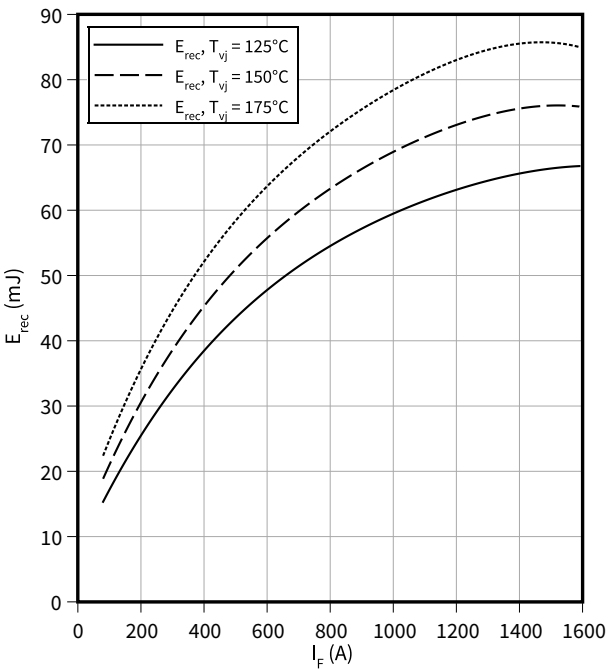
$I_F = f(V_F)$



Switching losses (typical), Diode, Inverter

$E_{rec} = f(I_F)$

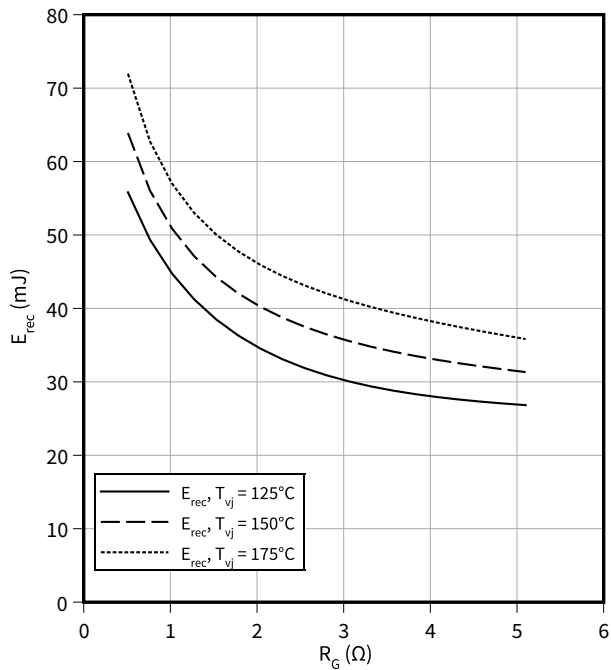
$R_{Gon} = 0.51\ \Omega, V_{CE} = 600\ \text{V}$



Switching losses (typical), Diode, Inverter

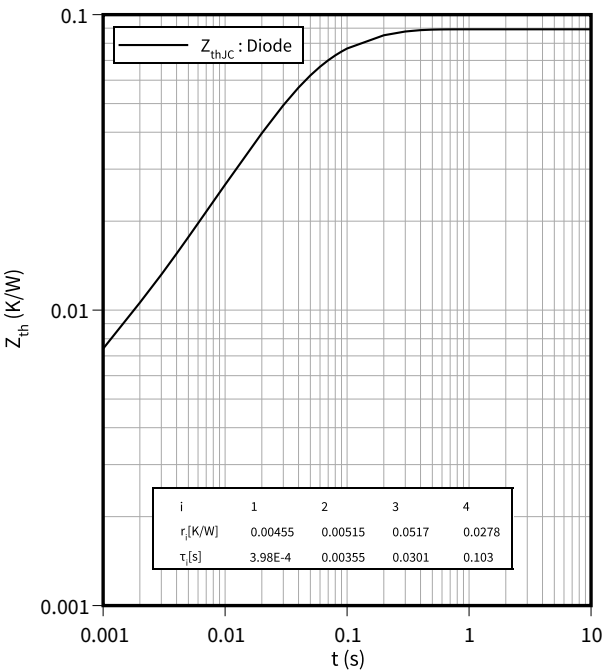
$E_{rec} = f(R_G)$

$V_{CE} = 600\ \text{V}, I_F = 800\ \text{A}$



Transient thermal impedance, Diode, Inverter

$Z_{th} = f(t)$



5 **Circuit diagram**

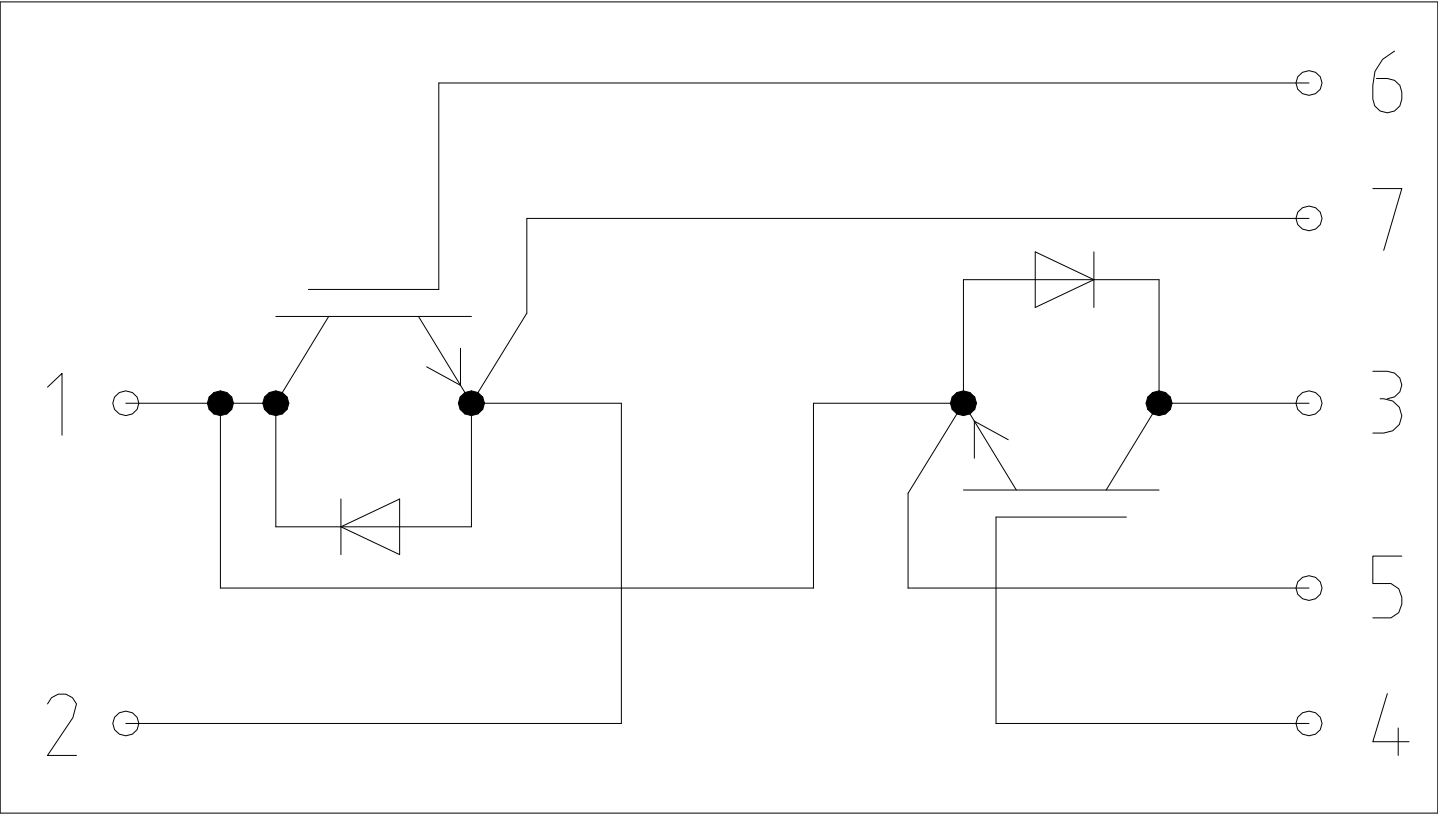


Figure 1

6 Package outlines

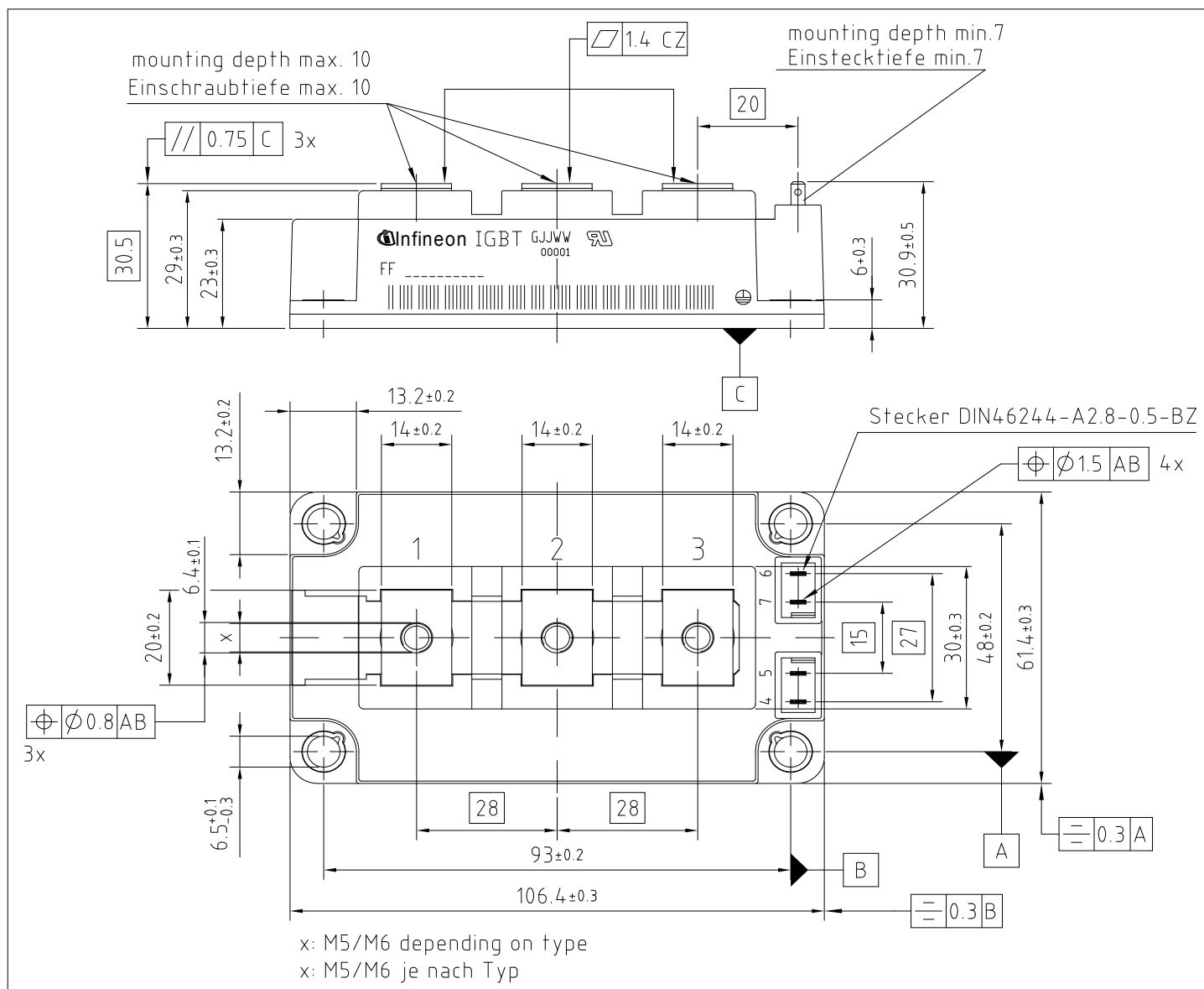


Figure 2

7 Module label code

Module label code			
Code format	Data Matrix		Barcode Code128
Encoding	ASCII text		Code Set A
Symbol size	16x16		23 digits
Standard	IEC24720 and IEC16022		IEC8859-1
Code content	Content	Digit	Example
	Module serial number	1 – 5	71549
	Module material number	6 - 11	142846
	Production order number	12 - 19	55054991
	Date code (production year)	20 – 21	15
	Date code (production week)	22 – 23	30
Example	 7154914284655054991153071549142846550549911530		

Figure 3

Revision history

Document revision	Date of release	Description of changes
V1.0	2020-06-19	Target datasheet
V1.1	2020-08-21	Target datasheet
n/a	2020-09-01	Datasheet migrated to a new system with a new layout and new revision number schema: target or preliminary datasheet = 0.xy; final datasheet = 1.xy
0.10	2021-09-02	Target datasheet
0.30	2021-11-15	Target datasheet
0.40	2021-12-17	Preliminary datasheet
1.00	2022-05-11	Final datasheet

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